



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PLCC4 SMD with IC
- ▶ 3535 IC 1.9t
- ▶ Red/Green/Blue

NOM59S09IC



Release Date: 14 March 2025 Version: A1.2



3535 IC-Integrated

RoHS
Compliant



FEATURES:

- **Package:** PLCC4 Top View Package with Integrated IC.
- **Forward Current:** 20/20/20mA*
- **Forward Voltage (typ.):** +3.0~+5.5V
- **Luminous Intensity (typ.):** 800/1400/320mcd
- **Colour:** Red/Green/Blue
- **Dominant Wavelength (typ.):** 622/520/467nm
- **Viewing Angle:** 120°
- **Materials:**
 - Die: AlGaInP/InGaN/InGaN
 - Resin: Silicone (Water Clear)
 - L/F Finish: Ag Plated
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Pixel:** Each R/G/B chip is 8bit, total of 16M colours can be displayed
- **Soldering methods:** Reflow soldering
- **MSL Level:** acc. to JEDEC Level 4
- **Packing:** 12mm tape with Max.500pcs/reel, ø180mm (7")

* in order of Red/Green/Blue

APPLICATIONS:

- Telecommunication
- Indicator
- Home Appliance
- Decoration Lighting
- Full Colour LED Strip
- Gaming Device
- Guardrail Tube

CHARACTERISTICS:

Absolute Maximum Characteristics ($T_a=25^{\circ}\text{C}$)

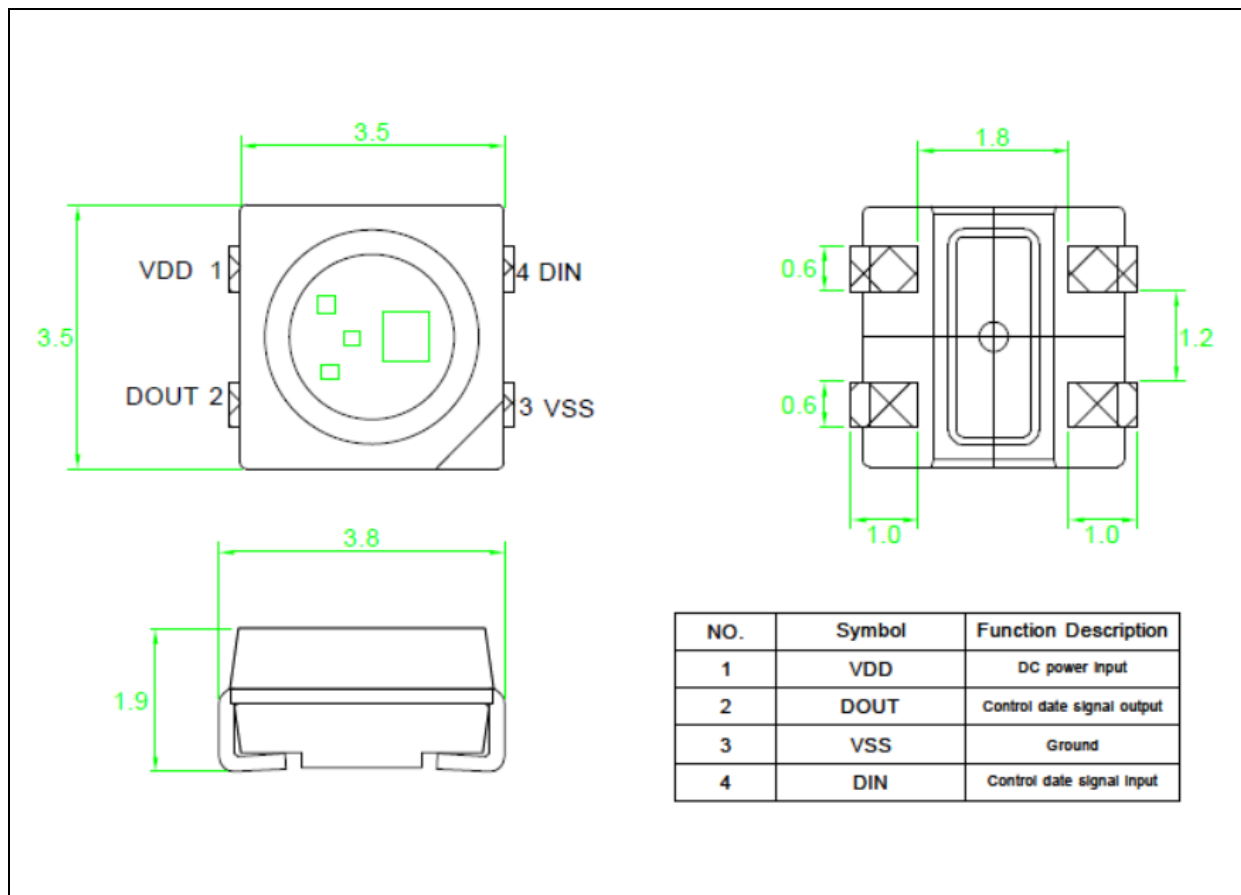
Parameter	Symbol	Ratings	Unit
LED Output Current	I_{OUT}	25	mA
Supply Voltage	V_{DD}	0 ~ +6.0	V
Operating Temperature	T_{OPR}	-40~+85	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-40~+100	$^{\circ}\text{C}$

Electrical & Optical Characteristics ($T_a=25^{\circ}\text{C}$)

Parameter		Symbol	Values			Unit	Test Condition
			Min.	Typ.	Max.		
Forward Voltage		V_F	3.0	5.0	5.5	V	---
Each R/G/B Current		I_{OL}	---	20	---	mA	$V_{DD}=5\text{V}$
Input High Voltage		V_{IH}	3.0	---	V_{DD}	V	DI
Input Low Voltage		V_{IL}	0	---	1.0	V	DI
Output High Voltage		V_{OH}	4.5	---	---	V	$I_{OH}=4\text{mA}$
Output Low Voltage		V_{OL}	---	---	0.4 V_{DD}	V	$I_{OL}=4\text{mA}$
Operation Current		I_{DD}	---	---	1.2	mA	R, G, B no load
Luminous Intensity	R	I_v	500	800	1250	mcd	$V_{DD}=5\text{V}$
	G		1000	1400	2000		
	B		200	320	800		
Dominant Wavelength	R	λ_D	615	622	630	nm	$V_{DD}=5\text{V}$
	G		515	520	530		
	B		460	467	475		
Viewing Angle		$2\theta_{1/2}$	---	120	---	deg	$V_{DD}=5\text{V}$

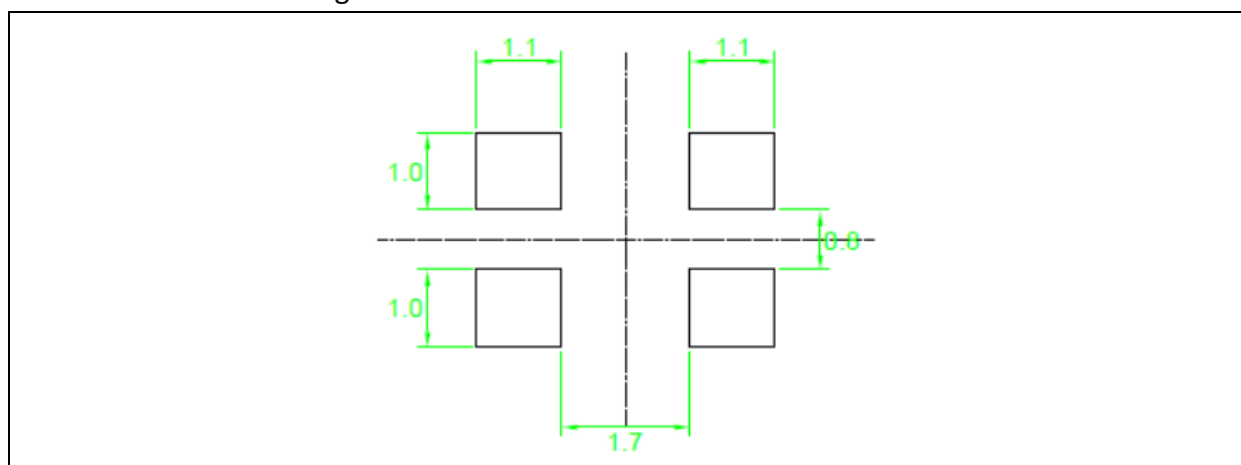
OUTLINE DIMENSION:

Package Dimension:



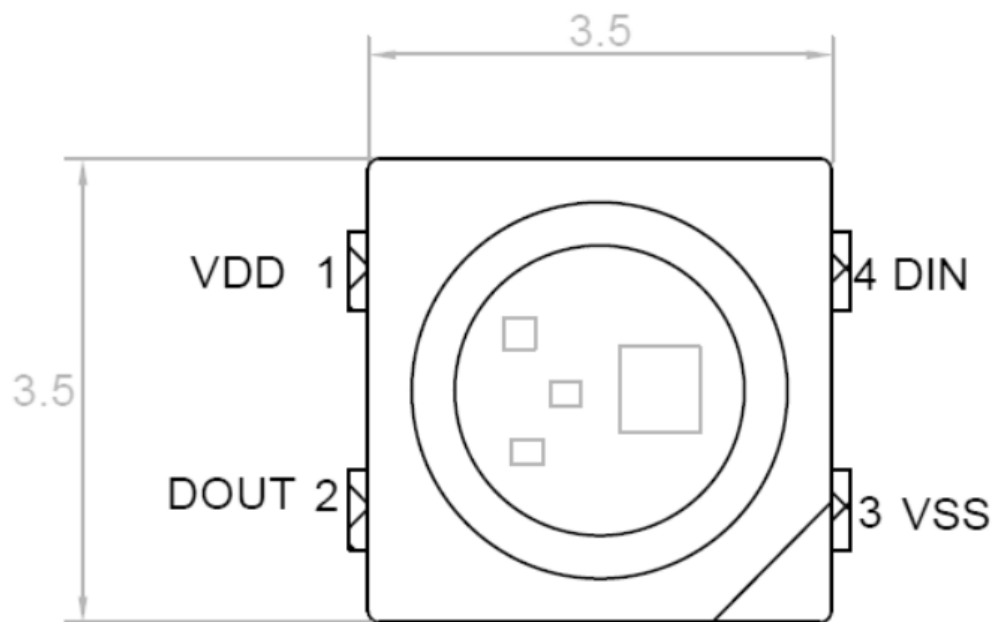
1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

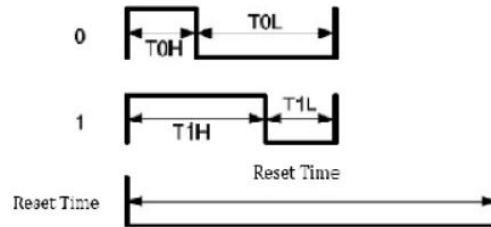
PIN CONFIGURATION:



No.	Symbol	Function Description
1	VDD	DC Power Input
2	DOUT	Control Data Signal Output
3	VSS	Ground
4	DIN	Control Data Signal Input

Function Description:

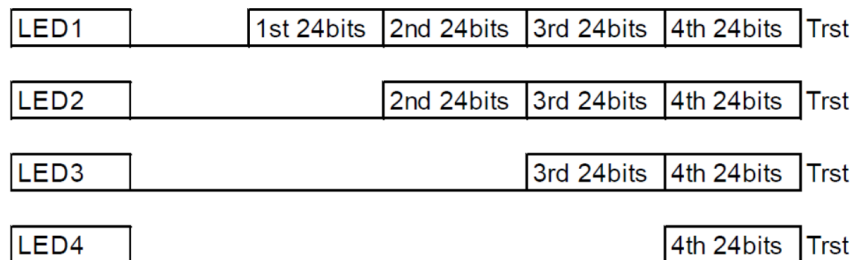
1. Timing Wave Form:



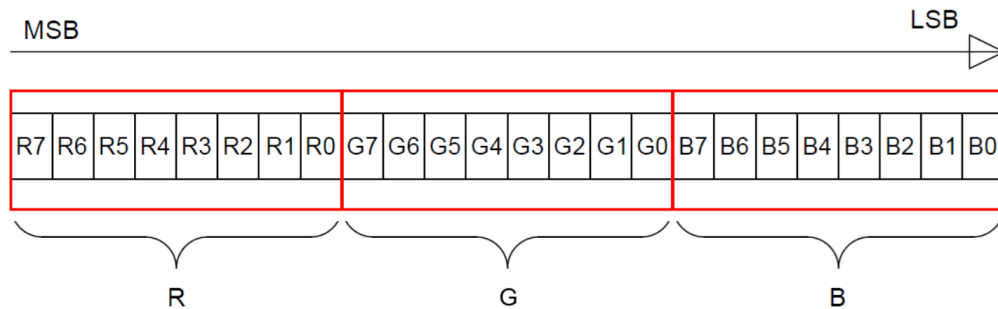
2. High Speed Mode:

Item	Description	min	Typical	Allowance	unit
T0H	0 code, High-level time		0.3	±0.15	us
T0L	0 code, Low-level time		0.9	±0.15	us
T1H	1 code, High-level time		0.9	±0.15	us
T1L	1 code, Low-level time		0.3	±0.15	us
Trst	Reset code, Low-level time	250			us

3. Data Communication:



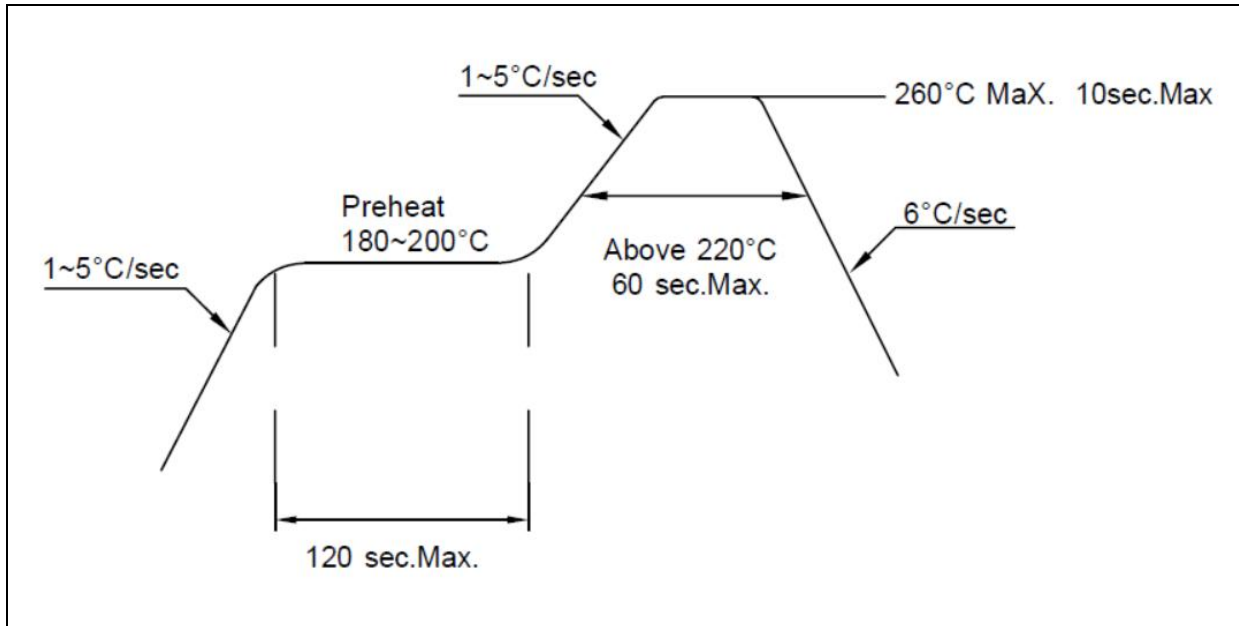
4. Single Data in 24bit for RGB:





RECOMMENDED SOLDERING PROFILE:

Lead-free Solder IR Reflow:



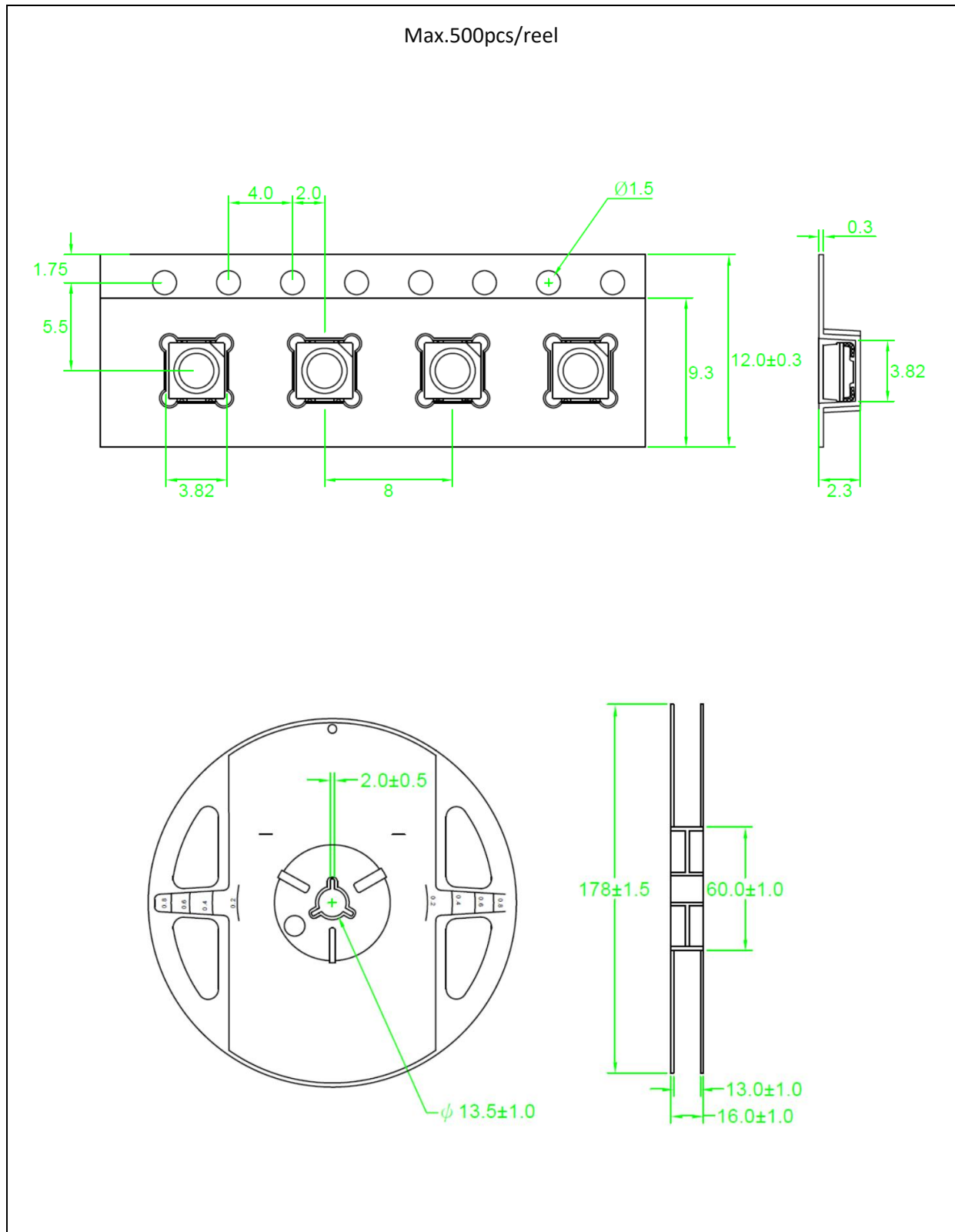
Note:

1. We recommend the reflow temperature 240°C ($\pm 5^\circ\text{C}$). The maximum soldering temperature should be limited to 260°C.
2. Maxima reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 72 hours. Otherwise, they should be kept in a damp-proof box with desiccating agent stored at R.H.<10% and apply baking before use.

Over-Current Proof:

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burn-out will happen.

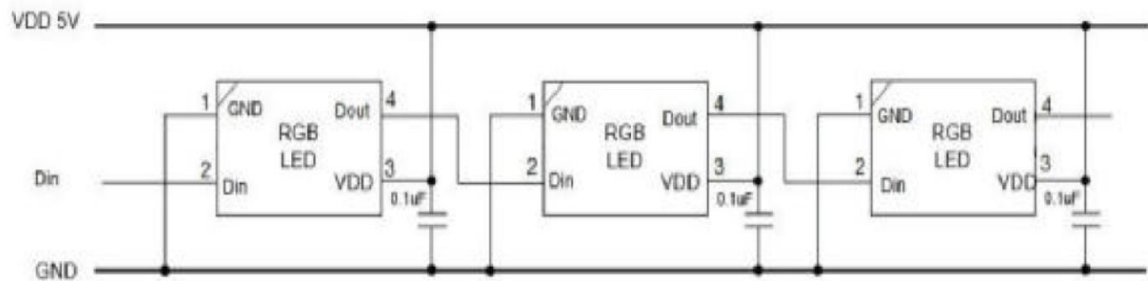
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as follows:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Recommended Route:



Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	26/04/2021	Datasheet set-up.
A1.1	22/02/2025	Revise colour sequence and bin table.
A1.2	14/03/2025	